

PCN# 20220127000.1**Qualification of new Fab site (FFAB or GFAB) using qualified Process Technology, Die Revision, and additional Assembly site/BOM options for select devices
Change Notification / Sample Request**

Date: January 31, 2022
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's previous announcement to close our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

PCN Team
SC Business Services

20220127000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TL2575-33IKTTR	null
TL2575HV-12IKTTR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20220127000.1	PCN Date:	January 31, 2022
Title:	Qualification of new Fab site (FFAB or GFAB) using qualified Process Technology, Die Revision, and additional Assembly site/BOM options for select devices		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Apr 30, 2022	Estimated Sample Availability:	Date provided at sample request.
Change Type:			
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Assembly Materials	
<input checked="" type="checkbox"/> Design	<input type="checkbox"/> Electrical Specification	<input type="checkbox"/> Mechanical Specification	
<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/> Wafer Bump Material	<input type="checkbox"/> Wafer Bump Process	
<input checked="" type="checkbox"/> Wafer Fab Site	<input checked="" type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Wafer Fab Process	
	<input type="checkbox"/> Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of a new fab using a qualified process technology (FFAB or GFAB, SLM) and assembly (TIEMA) site/BOM options for selected devices as listed below in the product affected section.

Current Fab Site			New Fab Site		
Fab Site	Process	Wafer Diameter	Fab Site	Process	Wafer Diameter
SFAB	JI1	150 mm	FFAB	SLM	200 mm
			GFAB	SLM	150 mm
			GFAB	SLM	200 mm


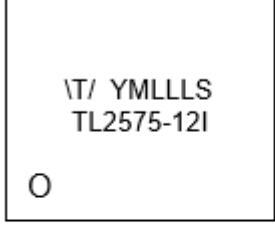
The die was also changed as a result of the process change.

Assembly Site material differences:

	TFME	GTBF	TIEMA
Mount compound	A-05	EY0000006	8052550
Mold compound	R-07	EN0000030	8096890

Qual details are provided in the Qual Data Section.

Package Marking Differences:

	GTBF/TFME	TIEMA
Sample marking	 <p>\T/ = TI LOGO YM = YEAR MONTH DATE CODE LLLL = ASSEMBLY LOT CODE S = ASSEMBLY SITE CODE O = NOTCH POSITION</p>	 <p>\T/ = TI LOGO YM = YEAR MONTH DATE CODE LLLL = ASSEMBLY LOT CODE S = ASSEMBLY SITE CODE O = NOTCH POSITION</p>
Notch position	Top middle	Bottom left

Package Outline Differences:

	GTBF/TFME	TIEMA
	<p>KTT Notes: All linear dimensions are in millimeters.</p>	<p>KTT0005B Notes: All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters.</p>
Total length (mm)	14.6 – 15.88	14.35 max
PCB mounting	Center of component aligned to center of pad	Shift component placement by 1.8mm towards the lead solder pad

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the change in status of environmental ratings (Change From/Change To) following implementation of this change.

Change From:			
RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> RoHS = Yes	<input checked="" type="checkbox"/> REACH = Yes	<input checked="" type="checkbox"/> Green = Yes	<input checked="" type="checkbox"/> IEC 62474 = Yes
Change To:			
RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> RoHS = Exempt-7(a)	<input checked="" type="checkbox"/> REACH = Affected	<input checked="" type="checkbox"/> Green = Yes	<input checked="" type="checkbox"/> IEC 62474 = Affected

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
FR-BIP-1	TID	DEU	Freising
GFAB8	GF8	GBR	Greenock

Die Rev:

Current	New
Die Rev [2P] G	Die Rev [2P] F

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TFME	NFM	CHN	Chongchuan
GTBF	GTF	CHN	Shatin
TIEMA	CU6	MYS	Melaka

Sample product shipping label (not actual product label)

Product Affected:

TL2575-05IKTTR	TL2575-33IKTTR	TL2575HV-05IKTTR	TL2575HV-15IKTTR
TL2575-12IKTTR	TL2575-ADJIKTTR	TL2575HV-12IKTTR	TL2575HV-ADJIKTTR

Change Qualification Report:

Approve Date 01/26/2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device TL2575	Qual Device: LM2577SX-ADJ
AC	Autoclave 121C	96 hours	3/231/0	
HBM	ESD - HBM	2000V	1/3/0	
HTOL	Life Test, 150C	300 hours	1/77/0	
HTSL	High Temp Storage Bake 150C	1000 hours	QBS	1/77/0
LU	Latch-up	125C	1/6/0	
THB	Temperature Humidity Bias 85C/85%RH	1000 hours	3/231/0	
TC	Temperature Cycle, -65/150C	500 cycles	3/231/0	

- QBS: Qual By Similarity

- Qual family TL2575 is qualified at LEVEL3-260CG

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified RoHS-Exempt and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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